

Supply Chain Explorer

By the Emerging Technology Observatory

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Ceramic packages

Protective ceramic packages, plastic substrates, or encapsulant resins may be bonded to a chip during the packaging process.

Country provision

- China (mainland)
- Germany
- Japan
- South Korea
- United States

Notable supplier companies

- Alent - United Kingdom
- Amkor - United States
- BASF - Germany
- Henkel - Germany
- Hitachi - Japan
- Kyocera - Japan
- LG - South Korea
- Mitsui High-Tec - Japan
- NGK - Japan
- QP Technologies - United States
- Sumitomo - Japan
- Tanaka - Japan
- Toray - Japan
- Yixing - China (mainland)
- Zhongwei - China (mainland)